

Product/ Process Change Notification

Product/ Process Change Notification				
1. PCN No.:	QPCN12026			
2. Subject:	ABS(STD GPP) bridge rectifiers, add further FE(Front End) & BE(Back End) manufacturing site			
3. To:	Refer to involved customer list			
4. Issued by:	Owen Wang			
5. Issue date:	24-Dec-2012			
6. Proposed first ship date for change:	25-Mar-2013			
7. Affected Product Identification				
Glass Passivated Bridge Rectifiers ABS package More details please see TSC involved P/N lis				
8. Change Description : (OLD Vs. NEW Co	omparison)			
Old:	New:			
 BE 1st source Taiwan Semiconductor YEW plant FE 1st & 2nd source Taiwan Semiconductor Li-Je and TEW plant 	 ➢ BE 2nd source subcontractor plant in China. ➢ FE 3rd source in China. 			
 ➤ Mold compound: EME-EK110G (Halogen Free) ➤ Mold compound: EME-EK1800G (Halogen 	Mold compound: EME-EK-120G (Halogen Free)			
Free) 9. Reason for Change:				
Manufacturing capacity enhancement and ris	k spread.			
10. Anticipated Impact: (form, fit, function, quality or reliability)				
1. Product outline: No cha 2. Inner construction changed: Lead-f				
3. Electrical specifications: No character N	nge nge nge nge			
11. Qualification plan/result:				
 Comparison report see attached PPAP is available on demand 				
12. Sample availability Date:	24-Dec-2012			
13. Tentative implementation date:	31-Jan-2013			
14. Remarks				
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)	31-Jan-2013			
16. Approved by:	Quayer Chen			



Product/ Process Change Notification Customer Approval Form_QPCN12026

(Please tick the field what is valid for you!)				
We agree with this proposed change and its schedule.				
We have object	tions			
■ We need more				
We need samp	le:			
Company:				
Name:				
Address:				
Signature:		Date:		